

DS34C87T CMOS Quad TRI-STATE Differential Line Driver

Check for Samples: [DS34C87T](#)

FEATURES

- TTL Input Compatible
- Typical Propagation Delays: 6 ns
- Typical Output Skew: 0.5 ns
- Outputs Won't Load Line When $V_{CC} = 0V$
- Meets the Requirements of EIA Standard RS-422
- Operation from Single 5V Supply
- TRI-STATE Outputs for Connection to System Buses
- Low Quiescent Current
- Available in Surface Mount

DESCRIPTION

The DS34C87T is a quad differential line driver designed for digital data transmission over balanced lines. The DS34C87T meets all the requirements of EIA standard RS-422 while retaining the low power characteristics of CMOS. This enables the construction of serial and terminal interfaces while maintaining minimal power consumption.

The DS34C87T accepts TTL or CMOS input levels and translates these to RS-422 output levels. This part uses special output circuitry that enables the individual drivers to power down without loading down the bus. This device has separate enable circuitry for each pair of the four drivers. The DS34C87T is pin compatible to the DS3487T.

All inputs are protected against damage due to electrostatic discharge by diodes to V_{CC} and ground.

Connection and Logic Diagrams

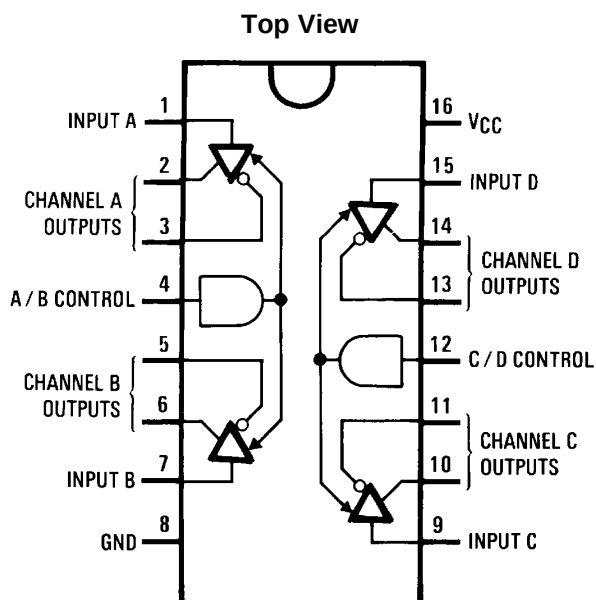

See [PIN DESCRIPTIONS](#) for details.

Figure 1. PDIP Package
See Package Numbers D0016A or NFG0016E

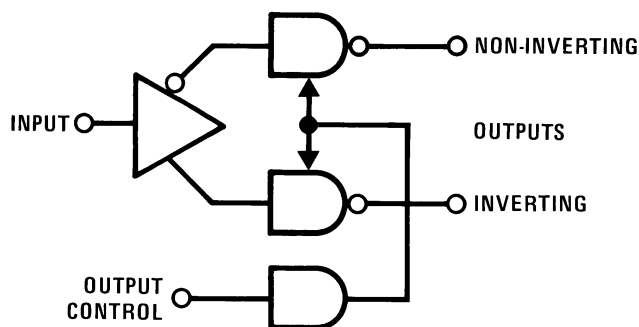


Figure 2. Logic Diagram



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Truth Table⁽¹⁾

Input	Control	Non-Inverting	Inverting
	Input	Output	Output
H	H	H	L
L	H	L	H
X	L	Z	Z

- (1) L = Low logic state
H = High logic state
X = Irrelevant
Z = TRI-STATE (high performance)



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings⁽¹⁾⁽²⁾⁽³⁾⁽⁴⁾

Supply Voltage (V_{CC})	-0.5 to 7.0V
DC Voltage (V_{IN})	-1.5 to $V_{CC} + 1.5V$
DC Output Voltage (V_{OUT})	-0.5 to 7V
Clamp Diode Current (I_{IK} , I_{OK})	± 20 mA
DC Output Current, per pin (I_{OUT})	± 150 mA
DC V_{CC} or GND Current (I_{CC})	± 150 mA
Storage Temperature Range (T_{STG})	-65°C to +150°C
Maximum Power Dissipation (P_D) @ 25°C ⁽⁵⁾	
PDIP Package	1736 mW
SOIC Package	1226 mW
Lead Temperature (T_L)	
(Soldering 4 sec)	260°C
This device does not meet 2000V ESD rating.⁽⁶⁾	

- (1) Unless otherwise specified, all voltages are referenced to ground. All currents into device pins are positive; all currents out of device pins are negative.
- (2) Absolute Maximum Ratings are those values beyond which the safety of the device cannot be specified. They are not meant to imply that the device should be operated at these limits. The table of "Electrical Characteristics" provide conditions for actual device operation.
- (3) ESD Rating: HBM (1.5 k Ω , 100 pF) Inputs $\geq 1500V$ Outputs $\geq 1000V$ EIAJ (0 Ω , 200 pF) All Pins $\geq 350V$
- (4) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/ Distributors for availability and specifications.
- (5) Ratings apply to ambient temperature at 25°C. Above this temperature derate NFG0016E Package 13.89 mW/°C, and D0016A Package 9.80 mW/°C.
- (6) ESD Rating: HBM (1.5 k Ω , 100 pF) Inputs $\geq 1500V$ Outputs $\geq 1000V$ EIAJ (0 Ω , 200 pF) All Pins $\geq 350V$

Operating Conditions

	Min	Max	Units
Supply Voltage (V_{CC})	4.50	5.50	V
DC Input or Output Voltage (V_{IN} , V_{OUT})	0	V_{CC}	V
Operating Temperature Range (T_A) DS34C87T	-40	+85	°C
Input Rise or Fall Times (t_r , t_f)		500	ns

DC Electrical Characteristics⁽¹⁾

$V_{CC} = 5V \pm 10\%$ (unless otherwise specified)

Parameter		Test Conditions	Min	Typ	Max	Units
V_{IH}	High Level Input Voltage		2.0			V
V_{IL}	Low Level Input Voltage				0.8	V
V_{OH}	High Level Output Voltage	$V_{IN} = V_{IH}$ or V_{IL} , $I_{OUT} = -20$ mA	2.5	3.4		V
V_{OL}	Low Level Output Voltage	$V_{IN} = V_{IH}$ or V_{IL} , $I_{OUT} = 48$ mA		0.3	0.5	V
V_T	Differential Output Voltage	$R_L = 100 \Omega$ See ⁽²⁾	2.0	3.1		V
$ V_T - \overline{V_T} $	Difference In Differential Output	$R_L = 100 \Omega$ See ⁽²⁾			0.4	V
V_{OS}	Common Mode Output Voltage	$R_L = 100 \Omega$ See ⁽²⁾		2.0	3.0	V
$ V_{OS} - \overline{V_{OS}} $	Difference In Common Mode Output	$R_L = 100 \Omega$ See ⁽²⁾			0.4	V
I_{IN}	Input Current	$V_{IN} = V_{CC}, GND, V_{IH},$ or V_{IL}			± 1.0	μA
I_{CC}	Quiescent Supply Current	$I_{OUT} = 0 \mu A$, $V_{IN} = V_{CC}$ or GND $V_{IN} = 2.4V$ or $0.5V$ ⁽³⁾		200 0.8	500 2.0	μA mA
I_{OZ}	TRI-STATE Output Leakage Current	$V_{OUT} = V_{CC}$ or GND Control = V_{IL}		± 0.5	± 5.0	μA
I_{SC}	Output Short Circuit Current	$V_{IN} = V_{CC}$ or GND See ⁽²⁾ and ⁽⁴⁾	-30		-150	mA
I_{OFF}	Power Off Output Leakage Current	$V_{CC} = 0V$ $V_{OUT} = 6V$ See ⁽²⁾ $V_{OUT} = -0.25V$			100 -100	μA μA

(1) Unless otherwise specified, min/max limits apply across the $-40^\circ C$ to $85^\circ C$ temperature range. All typicals are given for $V_{CC} = 5V$ and $T_A = 25^\circ C$.

(2) See EIA Specification RS-422 for exact test conditions.

(3) Measured per input. All other inputs at V_{CC} or GND.

(4) This is the current sourced when a high output is shorted to ground. Only one output at a time should be shorted.

Switching Characteristics⁽¹⁾

$V_{CC} = 5V \pm 10\%$, t_r , $t_f \leq 6$ ns (Figure 3, Figure 4, Figure 5, Figure 6)

Parameter		Test Conditions	Min	Typ	Max	Units
t_{PLH} , t_{PHL}	Propagation Delay Input to Output	S1 Open		6	11	ns
Skew	See ⁽²⁾	S1 Open		0.5	3	ns
t_{TLH} , t_{THL}	Differential Output Rise And Fall Times	S1 Open		6	10	ns
t_{PZH}	Output Enable Time	S1 Closed		12	25	ns
t_{PZL}	Output Enable Time	S1 Closed		13	26	ns
t_{PHZ}	Output Disable Time ⁽³⁾	S1 Closed		4	8	ns
t_{PLZ}	Output Disable Time ⁽³⁾	S1 Closed		6	12	ns
C_{PD}	Power Dissipation Capacitance ⁽⁴⁾			100		pF
C_{IN}	Input Capacitance			6		pF

- (1) Unless otherwise specified, min/max limits apply across the -40°C to 85°C temperature range. All typicals are given for $V_{CC} = 5V$ and $T_A = 25^{\circ}\text{C}$.
- (2) Skew is defined as the difference in propagation delays between complementary outputs at the 50% point.
- (3) Output disable time is the delay from the control input being switched to the output transistors turning off. The actual disable times are less than indicated due to the delay added by the RC time constant of the load.
- (4) C_{PD} determines the no load dynamic power consumption, $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$, and the no load dynamic current consumption, $I_S = C_{PD} V_{CC} f + I_{CC}$.

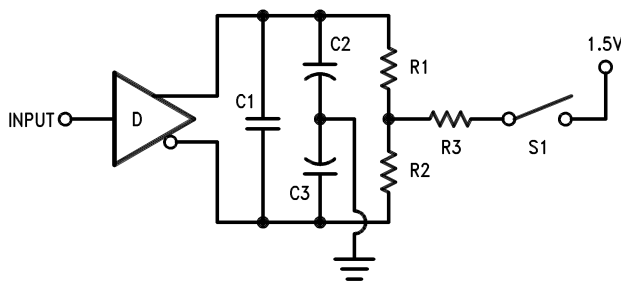
Comparison Table of Switching Characteristics into “LS-Type” Load⁽¹⁾

$V_{CC} = 5V$, $T_A = +25^{\circ}\text{C}$, $t_r \leq 6$ ns, $t_f \leq 6$ ns (Figure 6, Figure 7, Figure 8, Figure 9, Figure 10, Figure 11)

Parameter		Test Conditions	DS34C87		DS3487		Units
			Typ	Max	Typ	Max	
t_{PLH} , t_{PHL}	Propagation Delay Input to Output		6	10	10	15	ns
Skew	See ⁽²⁾		1.5	2.0			ns
t_{THL} , t_{TLH}	Differential Output Rise and Fall Times		4	7	10	15	ns
t_{PHZ}	Output Disable Time See ⁽³⁾	$C_L = 50$ pF, $R_L = 200\Omega$, S1 Closed, S2 Closed	8	11	17	25	ns
t_{PLZ}	Output Disable Time See ⁽³⁾	$C_L = 50$ pF, $R_L = 200\Omega$, S1 Closed, S2 Closed	7	10	15	25	ns
t_{PZH}	Output Enable Time	$C_L = 50$ pF, $R_L = \infty$, S1 Open, S2 Closed	11	19	11	25	ns
t_{PZL}	Output Enable Time	$C_L = 50$ pF, $R_L = 200\Omega$, S1 Closed, S2 Open	14	21	15	25	ns

- (1) This table is provided for comparison purposes only. The values in this table for the DS34C87 reflect the performance of the device but are not tested or ensured.
- (2) Skew is defined as the difference in propagation delays between complementary outputs at the 50% point.
- (3) Output disable time is the delay from the control input being switched to the output transistors turning off. The actual disable times are less than indicated due to the delay added by the RC time constant of the load.

AC TEST CIRCUIT AND SWITCHING TIME WAVEFORMS



Note: C1 = C2 = C3 = 40 pF (including Probe and Jig Capacitance), R1 = R2 = 50Ω, R3 = 500Ω

Figure 3. AC Test Circuit

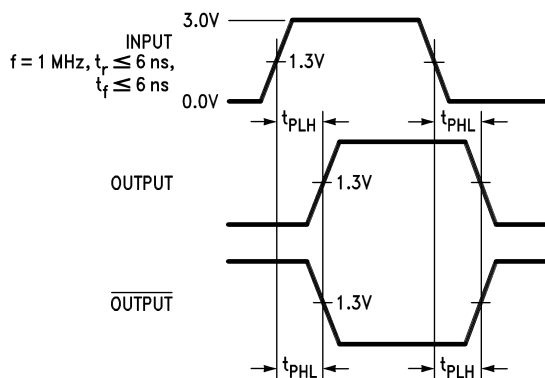


Figure 4. Propagation Delays

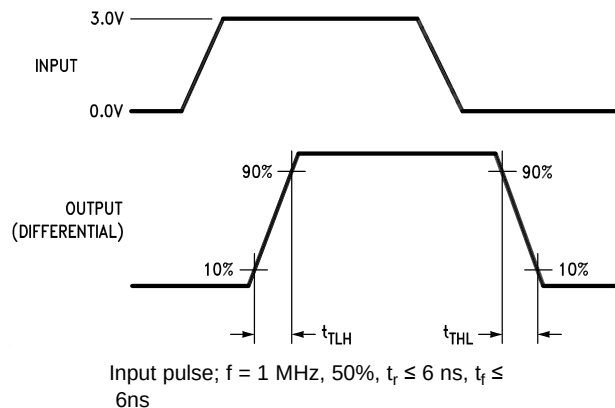


Figure 6. Differential Rise and Fall Times

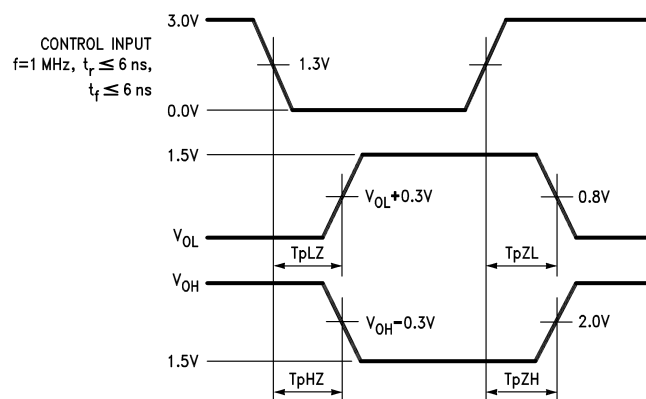


Figure 5. Enable and Disable Times

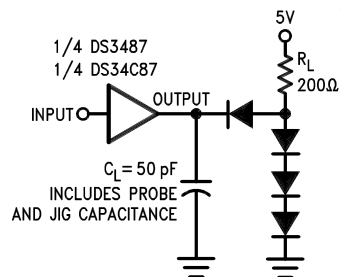


Figure 7. Propagation Delays Test Circuit for "LS-Type" Load

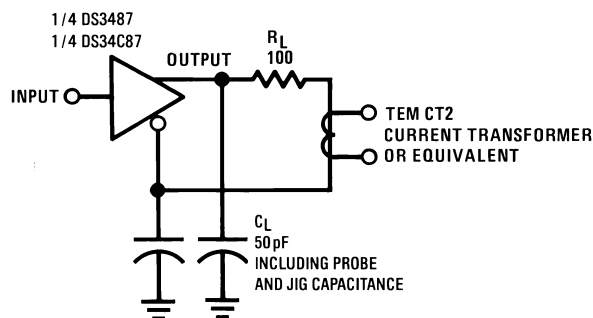


Figure 8. Differential Rise and Fall Times Test Circuit for “LS-Type” Load

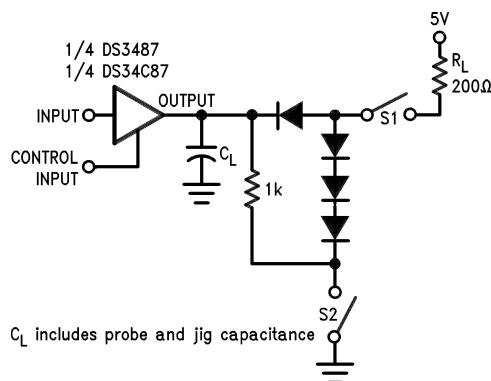


Figure 9. Load Enable and Disable Times Test Circuit for “LS-Type” Load

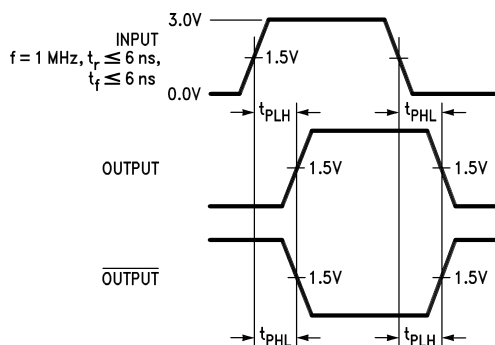


Figure 10. Load Propagation Delays for “LS-Type” Load

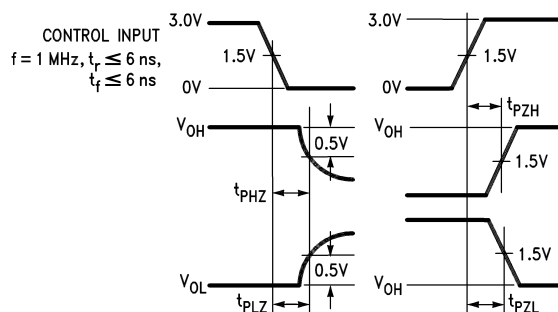
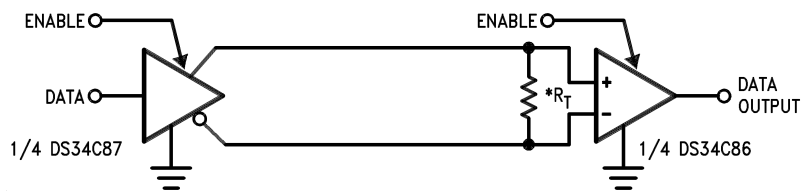


Figure 11. Load Enable and Disable Times for “LS-Type” Load

TYPICAL APPLICATIONS



* R_T is optional although highly recommended to reduce reflection.

PIN DESCRIPTIONS

Pin Number (PDIP or SOIC package)	Pin Name	Function
1	INPUT A	Channel A - TTL/CMOS input
2	OUTPUT A - True	True Output for Channel A, RS422 Levels
3	OUTPUT A - Inverting	Inverting Output for Channel A, RS422 Levels
4	A/B CONTROL	Enable Pin for Channels A and B, Active High, TTL/CMOS Levels
5	OUTPUT B - Inverting	Inverting Output for Channel B, RS422 Levels
6	OUTPUT B - True	True Output for Channel B, RS422 Levels
7	INPUT B	Channel B - TTL/CMOS input
8	GND	Ground Pin (0 V)
9	INPUT C	Channel C - TTL/CMOS input
10	OUTPUT C - True	True Output for Channel C, RS422 Levels
11	OUTPUT C - Inverting	Inverting Output for Channel C, RS422 Levels
12	C/D CONTROL	Enable Pin for Channels C and D, Active High, TTL/CMOS Levels
13	OUTPUT D - Inverting	Inverting Output for Channel D, RS422 Levels
14	OUTPUT D - True	True Output for Channel D, RS422 Levels
15	INPUT D	Channel D - TTL/CMOS input
16	V _{CC}	Power Supply Pin, 5.0V typical

REVISION HISTORY

Changes from Revision A (April 2013) to Revision B	Page
• Changed layout of National Data Sheet to TI format	7

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
DS34C87TM/NOPB	Active	Production	SOIC (D) 16	48 TUBE	Yes	Call TI Sn	Level-1-260C-UNLIM	-40 to 85	DS34C87TM
DS34C87TM/NOPB.A	Active	Production	SOIC (D) 16	48 TUBE	Yes	SN	Level-1-260C-UNLIM	-40 to 85	DS34C87TM
DS34C87TMX/NOPB	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	DS34C87TM
DS34C87TMX/NOPB.A	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	DS34C87TM

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

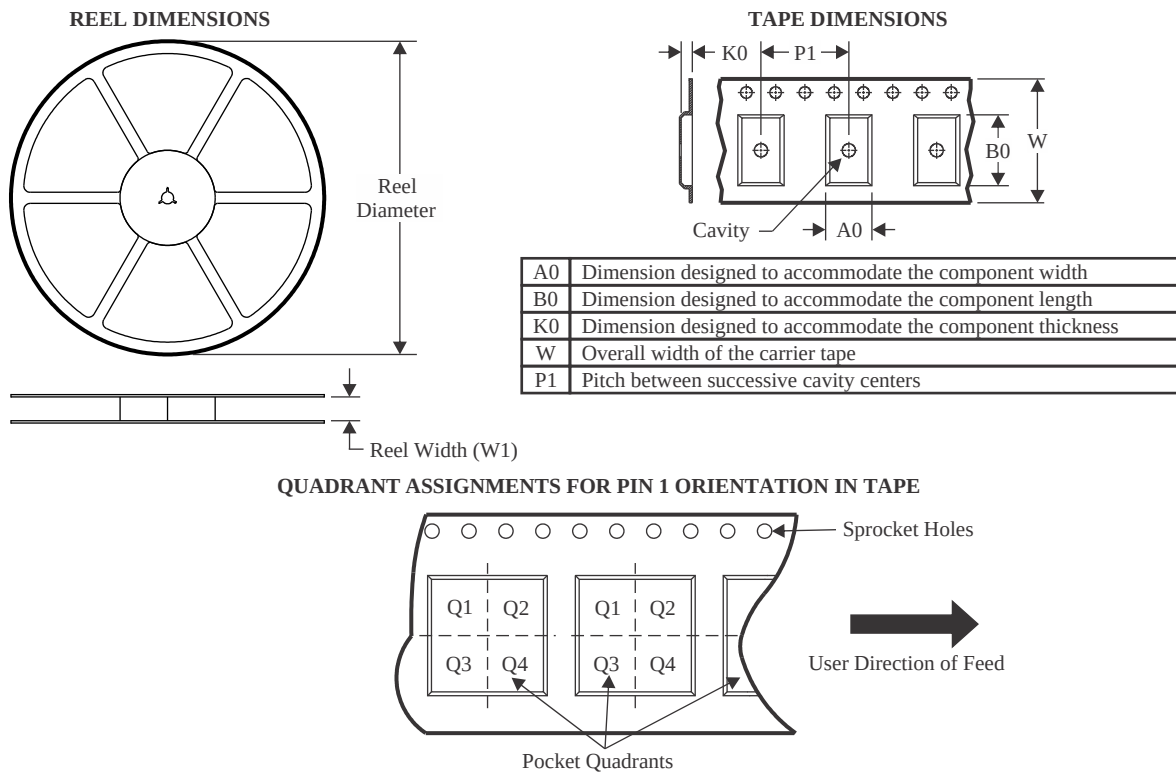
⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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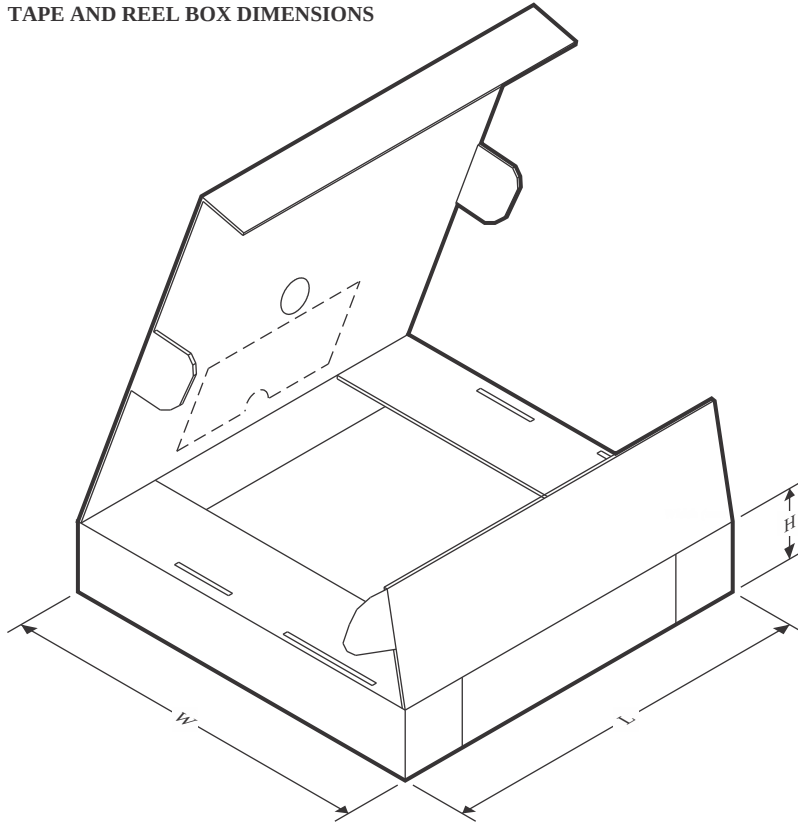
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
DS34C87TMX/NOPB	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.3	8.0	16.0	Q1

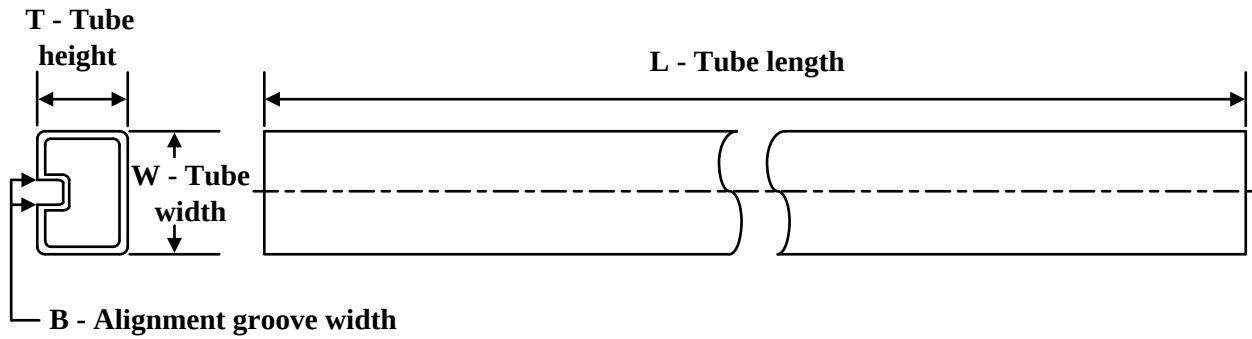
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
DS34C87TMX/NOPB	SOIC	D	16	2500	356.0	356.0	35.0

TUBE

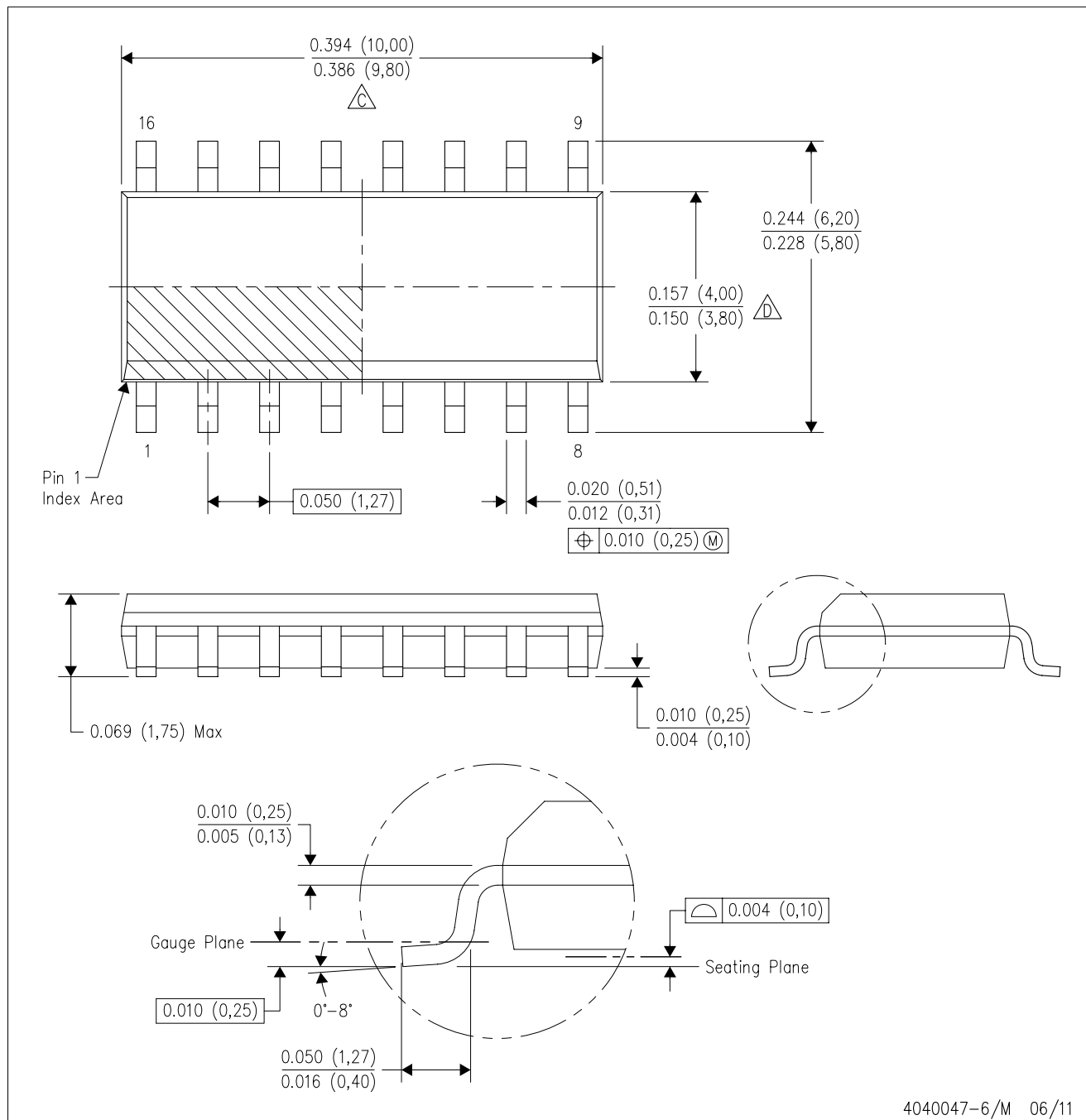


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
DS34C87TM/NOPB	D	SOIC	16	48	495	8	4064	3.05
DS34C87TM/NOPB.A	D	SOIC	16	48	495	8	4064	3.05

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

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